MW39962AE

Diagonal 11 mm (type-2/3) FIT CCD Area Image Sensor

Overview

The MW39962AE is a type-2/3 2.2M-pixel frame interline transfer (FIT-CCD) solid state image sensor.

This device uses photodiodes in the opto-electric conversion section and CCDs for signal read-out. The electronic shutter function allows for an exposure time of 1/10 000 seconds. Further, it features high sensitivity, low noise, broad dynamic range and low smear level.

The device has a total of $2\,182\,860$ pixels ($2\,010$ horizontal $\times\,1\,086$ vertical) and provides stable and clear images with a resolution of $1\,100$ horizontal and 730 vertical TV lines.

Part Number	CCD size	System	Color or B/W
MW39962AE	11 mm (type-2/3)	HDTV	B/W

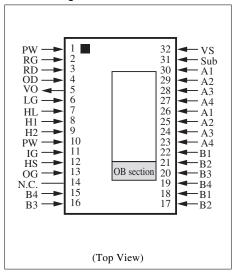
■ Features

- Effective pixel number: 1936 (horizontal) × 1086 (vertical)
- High sensitivity
- High resolution
- Low smear level
- Continuously variable-speed electronic shutter function
- Frame interline transfer system

Applications

- Broadcasting and professional use camera
- Front-edge surveillance camera

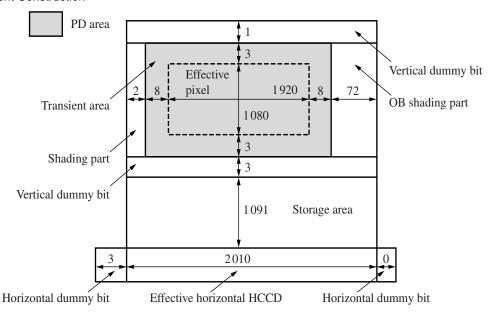
■ Pin Assignments



■ Device Configuration

Parameter	Value	Unit
Horizontal drive frequency	$f_{CK} = 2200 f_H = 74.25$	MHz
Total pixel number	2010 (H) × 1086 (V)	Pixel
Effective pixel number (including transient ones)	1936 (H) × 1086 (V)	Pixel
Effective pixel number	1920 (H) × 1080 (V)	Pixel
Pixel size	5.0 (H) × 5.0 (V)	μm ²
Effective image sensor size	9.6 (H) × 5.4 (V)	mm ²
Aspect ratio	16:9	H : V
Aspect ration error	0.0	%

• Element Construction



Note) The horizontal dummy bit is based on 2 gates = 1 unit.

■ Pin Descriptions

Pin No.	Symbol	Description	Pin No.	Symbol	Description
1	PW	P-well	11	IG	Horizontal input gate
2	RG	Reset gate	12	HS	Horizontal input source
3	RD	Reset drain	13	OG	Output gate
4	OD	Output drain	14	N.C.	Non Connection
5	VO	Video output	15	B4	Storage area vertical CCD gate 4
6	LG	Output load transistor gate	16	В3	Storage area vertical CCD gate 3
7	HL	Horizontal CCD final gate	17	B2	Storage area vertical CCD gate 2
8	H1	Horizontal CCD gate 1	18	B1	Storage area vertical CCD gate 1
9	H2	Horizontal CCD gate 2	19	B4	Storage area vertical CCD gate 4
10	PW	P-well	20	В3	Storage area vertical CCD gate 3

MW39962AE

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■ Pin Descriptions (continued)

Pin No.	Symbol	Description	Pin No.	Symbol	Description
21	B2	Storage area vertical CCD gate 2	27	A4	Sensor area vertical CCD gate 4
22	B1	Storage area vertical CCD gate 1	28	A3	Sensor area vertical CCD gate 3
23	A4	Sensor area vertical CCD gate 4	29	A2	Sensor area vertical CCD gate 2
24	A3	Sensor area vertical CCD gate 3	30	A1	Sensor area vertical CCD gate 1
25	A2	Sensor area vertical CCD gate 2	31	Sub	Substrate
26	A1	Sensor area vertical CCD gate 1	32	VS	Vertical input source

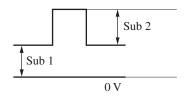
■ Absolute Maximum Ratings and Operating Conditions

Pin No. Para			Absolute maximum rating		Operating condition			Unit
PIII NO.	Parai	Parameter		Upper limit	Min	Тур	Max	Onit
1	PW		Reference voltage		_	0.0	_	V
2	RG	Amplitude	0	9.0	4.7	5.0	5.3	V
		Low	0	_	1.0	adj.	8.0	V
3	RD		0	18	14.3	14.5	14.7	V
4	OD		0	18	14.3	14.5	14.7	V
5	VO		_	_	_	_	_	V
6	LG		0	6	1.0	adj.	4.0	V
7	ϕ_{HL}	High	_	10	2.7	3.0	3.3	V
		Low	0	_	0.0	0.0	0.3	V
8	фн1	High	_	10	2.7	3.0	3.3	V
		Low	0	_	0.0	0.0	0.3	V
9	ф _{H2}	High	_	10	2.7	3.0	3.3	V
		Low	0	_	0.0	0.0	0.3	V
10	PW		Referenc	e voltage	_	0.0	_	V
11	IG		0	5	_	0.0	_	V
12	HS		0	18	15.7	16.0	16.3	V
13	OG		0	5	0.0	adj.	0.3	V
14	N.C.		_	_	_	_	_	_
15	ϕ_{B4}	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12	_	-9.3	-9.0	-8.7	V
16	ϕ_{B3}	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12	_	-9.3	-9.0	-8.7	V
17	ϕ_{B2}	Middle	_	18	- 0.3	0	0.3	V
		Low	-12	_	-9.3	-9.0	-8.7	V
18	фв1	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12	_	-9.3	-9.0	-8.7	V
19	ϕ_{B4}	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12		-9.3	-9.0	-8.7	V

■ Absolute Maximum Ratings and Operating Conditions (continued)

Din No.			Absolute maximum rating		Operating condition			Limit
Pin No.	Parar	neter	Lower limit	Upper limit	Min	Тур	Max	Unit
20	ф _{В3}	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12	_	-9.3	-9.0	-8.7	V
21	ϕ_{B2}	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12	_	-9.3	-9.0	-8.7	V
22	ϕ_{B1}	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12	_	-9.3	-9.0	-8.7	V
23	ϕ_{A4}	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12	_	-8.3	-8.0	-7.7	V
24	ϕ_{A3}	High	_	18	14.7	15.0	15.3	V
		Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12		-8.3	-8.0	-7.7	V
25	ϕ_{A2}	Middle	_	18	0.7	1.0	1.3	V
		Low	-12	_	-8.3	-8.0	-7.7	V
26	ϕ_{A1}	High	_	18	14.7	15.0	15.3	V
		Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12	_	-8.3	-8.0	-7.7	V
27	ϕ_{A4}	Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12		-8.3	-8.0	-7.7	V
28	ϕ_{A3}	High	_	18	14.7	15.0	15.3	V
		Middle	_	18	- 0.3	0.0	0.3	V
		Low	-12		-8.3	-8.0	-7.7	V
29	ϕ_{A2}	Middle	_	18	0.7	1.0	1.3	V
		Low	-12		-8.3	-8.0	-7.7	V
30	ϕ_{A1}	High	_	18	14.7	15.0	15.3	V
		Middle	_	18	- 0.3	0	0.3	V
		Low	-12		-8.3	-8.0	-7.7	V
31	Sub *1	1	0	40 *2	3.0	adj.	14.0	V
		2	0	+0	24.0	25.0	26.0	V
32	VS		0	18	15.7	16.0	16.3	V
Operati	ng temperatur	re	-10	60	_	25	_	°C
Storage	temperature		-30	70	_	_	_	°C

Note) *1: Sub pulse at the electronic shutter



*2 : Upper limit of Sub maximum rating: Sub 1 + Sub 2 \leq 40 V

■ Image Sensor Characteristics T_a = 25°C

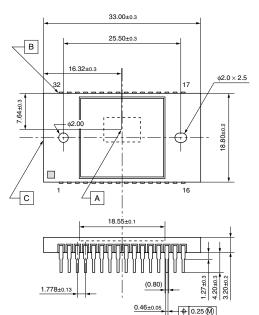
Parameter		Conditions	Min	Тур	Max	Unit	Remarks
Saturation output		F value adjust	650	800	_	mV	at CCD out
							(Minimum point in image)
Standard output		J chart standard light	140	155	_	mV	at CCD out
		intensity					
Image lag		1/10 light intensity	_	0		%	Able to be swept out
							directly to substrate
Vertical smear		1/10 V	_	-127	-124	dB	Ratio to standard output
							2 MHz driving
Dark	Н	60°C, dark condition	_	_	2	mV	at CCD out
shading	shading V						
Electronic shutter		Specified driving	No abnormality within 1/100 to 1/2000 seconds				econds

Note) 1. The substrate voltage (Sub 1) should be adjusted to the minimum voltage that would not cause blooming, overflow and injection at image sensor of light input of 1600 times the standard light intensity.

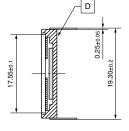
2. The standard light intensity is the one when the exposure is done at an aperture of F/11 using a light source of 2856K and 920 nt and placing a color temperature conversion filter LB-40 (HOYA) and an IR cutting filter CAW-500S (t = 2.5 mm) in the light path.

■ Package Dimensions (unit: mm)

• WDIP032-G-0750A (Lead-free package)



Tolerance: ±0.20 unless otherwise specified



- The package center does not meet the center of the effective pixel area.
 A is the center of the effective pixel area.
- The reference of a vertical direction(V) is the side B.
 The reference of a horizontal direction(H) is the side C.
 The reference of a height direction is the package bottom D.
- 3. The rotation precision of the effective pixel area: maximum $\pm 1.5^{\circ}$
- 4. The distance from the package bottom D to the effective pixel area : $1.69 \text{ mm} \pm 0.3 \text{ mm}$
- 5. The tilt of the effective pixel area toward the package bottom D : Up to 60 μm (D' = D_O \pm max. 0.03 mm)
- 6. The thickness of the seal glass is: 0.7 mm \pm 0.1 mm, and the refractive index: 1.50

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